

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently amended) A resin-encapsulated semiconductor device, comprising:
 - a die pad provided by removing thinning a lower portion of a lead frame;
 - a semiconductor chip mounted on the die pad;
 - a plurality of leads provided by removing thinning an upper portion of the lead frame;
 - a connection member for connecting the semiconductor chip and the lead with each other;
 - a plurality of suspension leads connected to the die pad; and
 - an encapsulation resin for encapsulating therein the die pad, the semiconductor chip, the leads, the connection member and the suspension leads, with a bottom surface and an outer side surface of each lead being exposed as an external terminal, wherein:
 - an upper surface of the die pad is located higher than an upper surface of the lead; and
 - a lower surface of the die pad is located higher than a lower surface of the lead; and
 - the suspension leads are not bent in a bending process.
2. (Original) The resin-encapsulated semiconductor device of claim 1, wherein:
 - the semiconductor chip is mounted with its principal surface facing up; and
 - the connection member is a thin metal wire.
3. (Original) The resin-encapsulated semiconductor device of claim 1, wherein:
 - the semiconductor chip is mounted with its principal surface facing down; and
 - the connection member is a bump made of a metal.
4. (Original) The resin-encapsulated semiconductor device of claim 1, wherein at least a portion of the semiconductor chip overlaps with the lead as viewed from above.

5. (Original) The resin-encapsulated semiconductor device of claim 1, wherein at least a portion of each of the die pad and the lead has a thickness of 100 μm to 150 μm .

6-9. (Cancelled)

10. (New) The resin-encapsulated semiconductor device of claim 1, wherein a connecting portion of each of the suspension leads which is connected to the die pad is formed by removing the lower portion of the lead frame.